17. (Amended) A method of manufacturing a light emitting device comprising:

irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light, thereby sublimating a vapor deposition material adhering to the component; and

exhausting the sublimated vapor deposition material.

Please add the following new claims:

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27 ~~18.~~ (New) The method according to claim 16 wherein said at least one selected from the group consisting of the infrared light, UV-light, and visible light is radiated by using a light source provided in the film-forming chamber.

28 ~~19.~~ (New) The method according to claim 16 wherein an irradiation surface of said at least one selected from the group consisting of the infrared light, UV-light, and visible light is in a rectangular or oblong shape.

29 ~~20.~~ (New) The method according to claim 16 further comprising a step of supplying a halogen containing gas into the film-forming chamber during sublimating the vapor deposition material.

30 ~~21.~~ (New) The method according to claim 16 further comprising a step of forming a plasma during exhausting.

31 ~~22.~~ (New) The method according to claim ~~21~~ 30 wherein said plasma is an oxygen plasma.

32 ~~23~~. (New) The method according to claim 16 wherein the vapor deposition material comprises an organic light emitting material.

33 ~~24~~. (New) The method according to claim 17 wherein said at least one selected from the group consisting of the infrared light, UV-light, and visible light is radiated by using a light source provided in the film-forming chamber.

34 ~~25~~. (New) The method according to claim 17 wherein an irradiation surface of said at least one selected from the group consisting of the infrared light, UV-light, and visible light is in a rectangular or oblong shape.

35 ~~26~~. (New) The method according to claim 17 further comprising a step of supplying a halogen containing gas into the film-forming chamber during sublimating the vapor deposition material.

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36 ~~27~~. (New) The method according to claim 17 further comprising a step of forming a plasma during exhausting.

37 ~~28~~. (New) The method according to claim 36 ~~27~~ wherein said plasma is an oxygen plasma.

38 ~~29~~. (New) The method according to claim 17 wherein the vapor deposition material comprises an organic light emitting material.

39 ~~30~~. (New) A method of manufacturing a display device comprising:

providing a substrate by a substrate holder in a film formation chamber;

forming a film comprising an organic material over the substrate by vapor deposition in the film formation chamber wherein said organic material is simultaneously deposited on said substrate holder;

removing said substrate from said reaction chamber after forming said film;

heating said organic material deposited on said substrate holder in said film formation chamber to vaporize said organic material;

exhausting the vaporized organic material from said film formation chamber.

40 ~~31.~~ (New) The method according to claim ~~30~~ 39 wherein said film comprising an organic material is a light emitting layer.

41 ~~32.~~ (New) The method according to claim ~~30~~ 39 further comprising a step of supplying a halogen containing gas into the film formation chamber during heating said organic material.

42 ~~33.~~ (New) The method according to claim ~~30~~ 39 further comprising exposing the vaporized organic material to a plasma.

~~34.~~ 43 (New) A method of manufacturing a display device comprising:

providing a substrate by a substrate holder in a film formation chamber wherein an adhesion preventing shield is provided between said substrate and an inner wall of the film formation chamber;

forming a film comprising an organic material over the substrate by vapor deposition in the film formation chamber wherein said organic material is simultaneously deposited on said adhesion preventing shield;

removing said substrate from said reaction chamber after forming said film;

heating said adhesion preventing shield to vaporize said organic material deposited on said adhesion preventing shield;

exhausting the vaporized organic material from said film formation chamber.

44 ~~35.~~ (New) The method according to claim ~~34~~ 43 wherein said film comprising an organic material is a light emitting layer.